Materials Declaration Form

IPC	**1752**	**Version**	**2**
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	**Subsectionals ***	A-D *** : Required Field**

Supplier Information			
Company Name *	STMicroelectronics	**Response Date ***	2016-05-17
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Floriana San Biagio	**Representative Title**	AMG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	**Representative Email ***	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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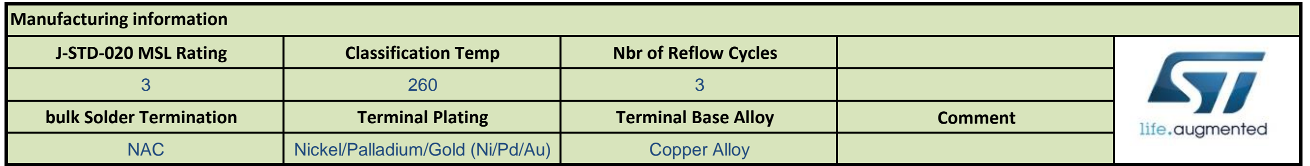
Legal Statement

Supplier Acceptance *	true	**Legal Declaration ***	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
	C56P*UI14AA5	A	ZY1A	2016-05-17
	Amount	**UoM**	**Unit type**	**ST ECOPACK Grade**
	34.00	mg	Each	ECOPACK® 2
,	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		



Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		
3	260	3		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	**Size**	**Nbr of instances**	**Shape**	
DSO	4.4x3x0.9	8	gull wing	
Comment	Package: 6P TSSOP 8 BODY 4.4 PITCH 0.65; MDF valid for SPV1040T-SPV1040TTR			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	**true**
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false

Exemption Id.	Description

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				**true**
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						**Mfr Item Name**	**CS6P*UI14AA5**					
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die	Other inorganic materials	2.587	mg	supplier	die	Silicon (Si)	7440-21-3		2.451	mg	947429	72088
				supplier	metallization	Aluminium (Al)	7429-90-5		0.025	mg	9664	735
				supplier	metallization	Tungsten (W)	7440-33-7		0.020	mg	7731	588
				supplier	Passivation	Silicon Nitride	12033-89-5		0.005	mg	1933	147
				supplier	Passivation	Silicon Oxide	7631-86-9		0.043	mg	16622	1265
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.002	mg	773	59
				supplier	back side metallization	Gold (Au)	7440-57-5		0.005	mg	1933	147
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.009	mg	3479	265
				supplier	back side metallization	Vanadium (V)	7440-62-2		0.001	mg	387	29
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.026	mg	10050	765
Leadframe	Copper & its alloys	16.989	mg	supplier	alloy	Copper (Cu)	7440-50-8		16.203	mg	953735	476559
				supplier	alloy	Nickel (Ni)	7440-02-0		0.505	mg	29725	14853
				supplier	alloy	Magnesium (Mg)	7439-95-4		0.025	mg	1472	735
				supplier	alloy	Silicon (Si)	7440-21-3		0.110	mg	6475	3235
	Nickel (Ni)			supplier	metallization	Nickel (Ni)	7440-02-0		0.133	mg	7829	3912
	Precious metals			supplier	metallization	Palladium (Pd)	7440-05-3		0.009	mg	530	265
	Precious metals			supplier	metallization	Gold (Au)	7440-57-5		0.004	mg	235	118
Die attach	Other Organic Materials	0.791	mg	supplier	glue	Silver (Ag)	7440-22-4		0.632	mg	798989	18588
				supplier	glue	Bisphenol F type epoxy resin	9003-36-5		0.063	mg	79646	1853
				supplier	glue	Epoxy resin	68475-94-5		0.024	mg	30341	706
				supplier	glue	2,6-Diglycidyl phenyl allyl ether	EC 417-470-1		0.024	mg	30341	706
				supplier	glue	Gamma Butyrolactone	96-48-0		0.024	mg	30341	706
				supplier	glue	Polyoxypropylenediamine	9046-10-0		0.024	mg	30341	706
Bonding wires	Precious metals	0.166	mg	supplier	wire	Gold (Au)	7440-57-5		0.166	mg	1000000	4882
Encapsulation	Other Organic Materials	13.467	mg	supplier	mold compound	Silica, vitreous	60676-86-0		11.663	mg	866043	343029
				supplier	mold compound	Epoxy Resin	Proprietary		1.010	mg	74998	29706
				supplier	mold compound	Phenol Resin	Proprietary		0.673	mg	49974	19794
				supplier	mold compound	Carbon black	1333-86-4		0.067	mg	4975	1971
				supplier	mold compound	Bismuth compound	7440-69-9		0.054	mg	4010	1588